IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

J. KONNO et al

Serial Number: 07/743,383

Group Art Unit: 1104

Filed: August 21, 1991

Examiner: G. Goudreau

For:

METHOD FOR PRODUCING SEMICONDUCTOR INTEGRATED CIRCUITS

AND APPARATUS USED IN SUCH METHOD

RESPONSE UNDER 37 CFR 1.115

Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

December 27, 1993

Dear Sir:

In response to the Official Action dated August 25, 1993, the period for response to which having been extended for one (1) month to expire December 25, 1993 by reason of a petition and a fee therefore filed herewith, kindly amend the above identified application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Twice Amended) A method for producing semiconductor integrated circuits, comprising the steps of:

a first step of selectively etching a metallic film formed on a surface of a substrate and exposed through a mask <u>made</u> of a resist which selectively covers said metallic film, by [using] effectively contacting said metal exposed through said mask with a